

## ROLE PROFILE

<b>Job Title:</b>	LED Packaging Manager		
<b>Reports To:</b>	Head of Engineering & Manufacturing	<b>Availability:</b>	< 3 months

### Job Summary

Enfis is a leader in the design and development of intelligent LED light engines for niche lighting, industrial and medical applications.

An opportunity has arisen in the engineering group for a LED Packaging Manager to provide technical leadership for the LED array research, development and manufacturing programmes within Enfis supporting the activities of the Head of Engineering and Manufacturing. The role will involve project management; instigating technical engineering improvements, leading key innovation activities, product development programmes and managing outsource manufacturing activities.

Experience of microelectronics/optoelectronics packaging, ideally involving LEDs is essential. The successful candidate will be able to translate product ideas and concepts into comprehensive technical specifications and through into manufacturing options utilising optimised cost approaches.

The role will involve research and development of new LED array packages and the optical coupling and heat removal methods for higher performance and lower cost. Key innovation will be supported by the filing of patents, where applicable.

### Essential Duties and Responsibilities:

- Design and Development of LED array products and LED chip packaging processes.
- Management of outsource manufacturing partners for LED Chip Packaging Processes
- Management of key suppliers of LED chips and base packages
- Leading R&D programmes and developing new programmes
- Generation of new ideas and innovative technology approaches applied to high performance LED arrays
- Interpret initial design concept brief and prepare technical specifications and manufacturing plans for new and existing products
- Prototyping of novel LED array solutions to test ideas, validate models and provide rapid demonstrations of Enfis technology.
- Research and develop novel optical coupling methods for enhancing light output from LED arrays.
- Research and develop novel thermal management methods for enhancing heat extraction from LED arrays.

- Communicate effectively to Head of Engineering and Manufacturing regarding the status and progress of projects undertaken on a regular and ongoing basis.

## **Education and Experience**

- PhD or BSc or equivalent – Physics or Engineering most relevant
- 3 years+ experience of technical leadership in high tech company
- Ideally experience of working in start-up or high growth small team environment
- Demonstrable track record of technology innovation achievements, i.e. patents, papers, conference presentations or other contributions.
- Project management experience in optoelectronics technology environment

## **Key Knowledge Requirements**

- Materials and Processes involved in microelectronics packaging including epoxy, soldering, wire bonding and encapsulation.
- Automated assembly processes for microelectronics (especially optoelectronic) components.
- Ideally with knowledge of LED chip manufacturing processes and performance requirements.
- Ability to source components and work with global suppliers.